

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

~~Claim 1:~~

1. (Currently amended) A method to improve the sputter deposition process, said method comprising the following steps:
- a) providing a vacuum;
 - b) providing an electrode in said vacuum;
 - c) providing a substrate in said vacuum, said substrate having no contact with said electrode;
 - d) providing a device in said vacuum; said device being in relative motion to said electrode and being in mechanical contact with said electrode over a contact zone;
- said device removing material from said electrode or said device applying material to said electrode, said material being in a solid state.

~~Claim 2:~~

2. (Currently amended) The method according to claim 1, wherein said device has a hardness, which is greater than, or equal to the hardness of the electrode or part thereof in order to remove material from said electrode.

~~Claim 3:~~

3. (Currently amended) The method according to claim 1, wherein said device has a hardness, which is smaller than, or equal to the hardness of the electrode or part thereof in order to apply material ~~from~~ to said electrode.

~~Claim 4:~~

4. (Currently amended) The method according to ~~any one of claim 1 to 3~~ claim 1, wherein said electrode is a cathode.

~~Claim 5:~~

5. (Currently amended) The method according to claim 4, wherein said cathode is a rotatable cylindrical target.

~~Claim 6:~~

6. (Currently amended) The method according to ~~any one of claim 1 to 3~~ claim 1, wherein said electrode is an anode.

~~Claim 7:~~

7. (Currently amended) The method according to claim 6, wherein said anode is a vacuum chamber wall or shield.

~~Claim 8:~~

8. (Currently amended) The method according to claim 6, wherein said anode is a rotatable cylindrical tube.

~~Claim 9:~~

9. (Currently amended) The method according to claim 6, wherein said anode is a rotatable brush.

~~Claim 10:~~

10. (Currently amended) The method according to ~~any one of claims 1 to 5~~ claim 4, wherein said target has an end zone that is not sputtered and wherein said contact zone overlaps with said end zone.

~~Claim 11:~~

11. (Currently amended) The method according to ~~any one of claims 1, 2, 3, 4, 5 or 10~~ claim 4, wherein said target has a zone of race track return and wherein said contact zone overlaps with said zone of race track return.

~~Claim 12:~~

12. (Currently amended) The method according to ~~any one of claims 1, 2, 3, 4, 5, 10 or 14~~ claim 4, wherein said target has an erosion zone and wherein said contact zone overlaps with said erosion zone.

~~Claim 13:~~

13. (Currently amended) The method according to claim 12, wherein said target is an ITO target.

~~Claim 14:~~

14. (Currently amended) A method according to ~~any one of claims 1 to 13~~ claim 1, wherein said device is intermittently in relative motion to said electrode and said device is intermittently in contact with said electrode.

~~Claim 15:~~

15. (Currently amended) A method according to ~~any one of claims 1 to 13~~ claim 1, wherein said device is continuously in relative motion to said electrode and said device is intermittently in contact with said electrode.

~~Claim 16:~~

16. (Currently amended) A method according to ~~any one of claims 1 to 13~~ claim 1, wherein said device is intermittently in relative motion to said electrode and said device is continuously in contact with said electrode.

~~Claim 17:~~

17. (Currently amended) A method according to ~~any one of claims 1 to 13~~ claim 1, wherein said device is continuously in relative motion to said electrode and said device is continuously in contact with said electrode.